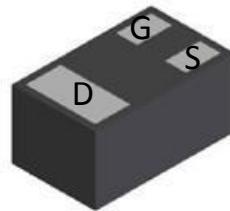


WNM2046A-3/TR

Single N-Channel, 20V, 0.6A, Power MOSFET

[Http://www.sh-willsemi.com](http://www.sh-willsemi.com)

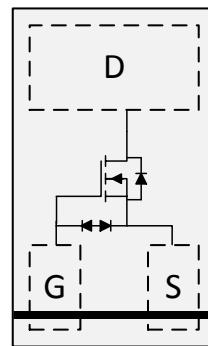
V_{DS} (V)	Typical R_{DS(on)} (Ω)
20	0.42 @ V _{GS} = 4.5V
	0.58 @ V _{GS} = 2.5V
	0.84 @ V _{GS} = 1.8V



DFN1006-3L

Descriptions

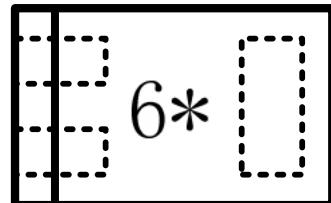
The WNM2046A-3/TR is N-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent R_{DS(ON)} with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit. Standard Product WNM2046A-3/TR is Pb-free.



Features

- Trench Technology
- Supper high density cell design
- Excellent ON resistance
- Extremely Low Threshold Voltage
- Small package DFN1006-3L

Pin configuration (Top view)



6 = Device Code

* = Month(A~z)

Applications

- DC/DC converters
- Power supply converters circuit
- Load/Power Switching for portable device

Marking

Order information

Device	Package	Shipping
WNM2046A-3/TR	DFN1006-3L	10K/Tape&Reel

Absolute Maximum ratings

Parameter		Symbol	10 s	Steady State	Unit
Drain-Source Voltage		V _{DS}	20	±10	V
Gate-Source Voltage		V _{GS}	±10		
Continuous Drain Current ^{a d}	T _A =25°C	I _D	0.6	0.55	A
	T _A =70°C		0.48	0.44	
Maximum Power Dissipation ^{a d}	T _A =25°C	P _D	0.32	0.27	W
	T _A =70°C		0.21	0.18	
Continuous Drain Current ^{b d}	T _A =25°C	I _D	0.57	0.52	A
	T _A =70°C		0.45	0.42	
Maximum Power Dissipation ^{b d}	T _A =25°C	P _D	0.29	0.25	W
	T _A =70°C		0.18	0.16	
Pulsed Drain Current ^c		I _{DM}	1.4		A
Operating Junction Temperature		T _J	-55 to 150		°C
Lead Temperature		T _L	260		°C
Storage Temperature Range		T _{stg}	-55 to 150		°C

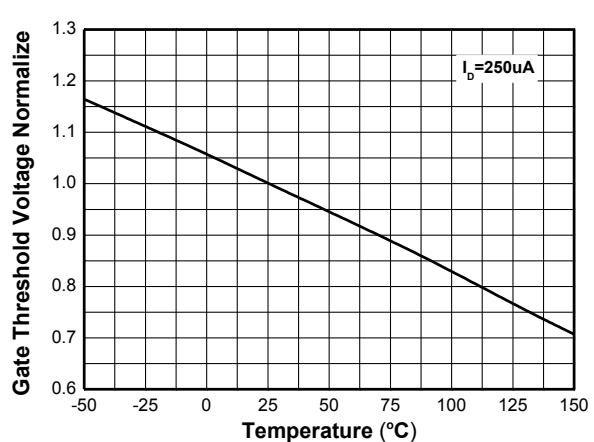
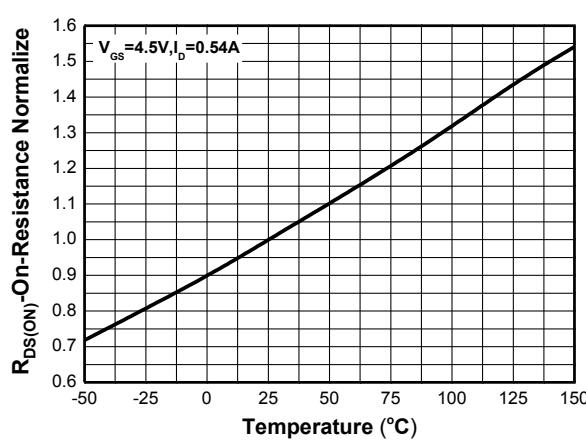
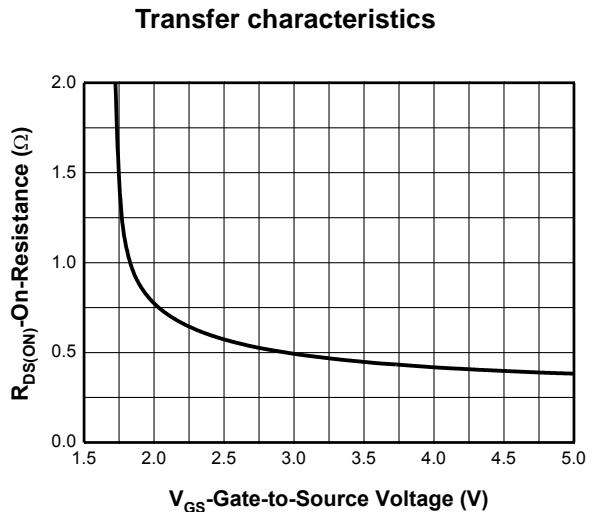
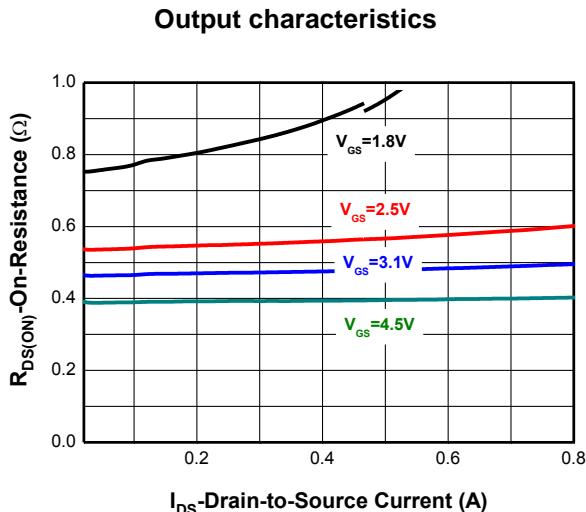
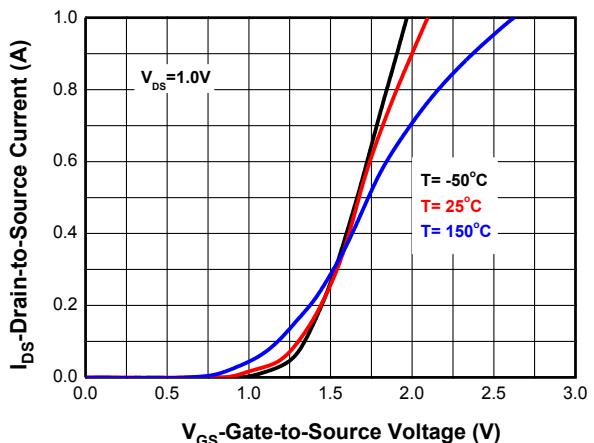
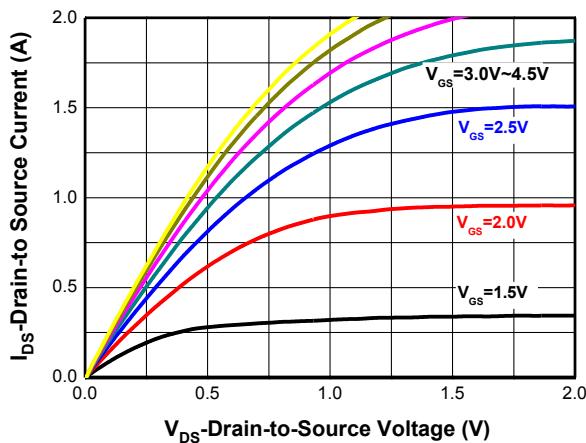
Thermal resistance ratings

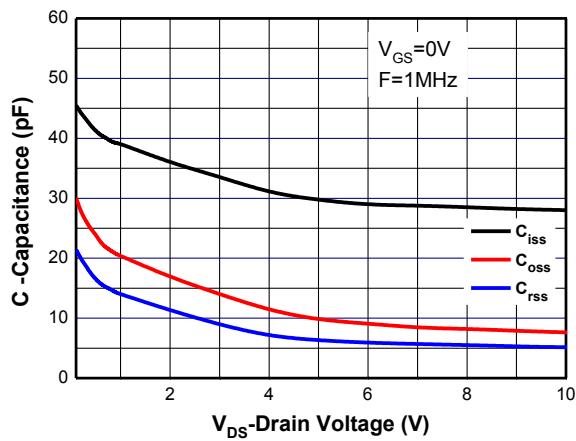
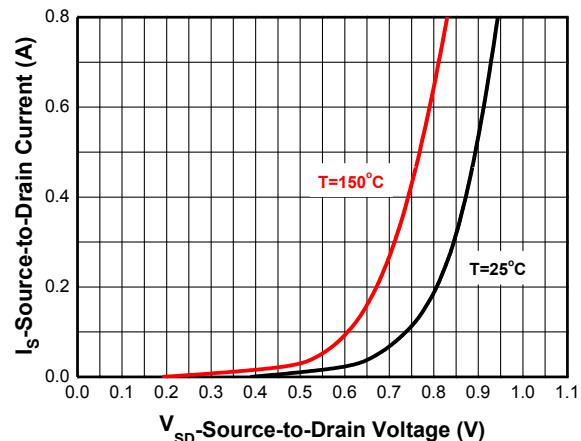
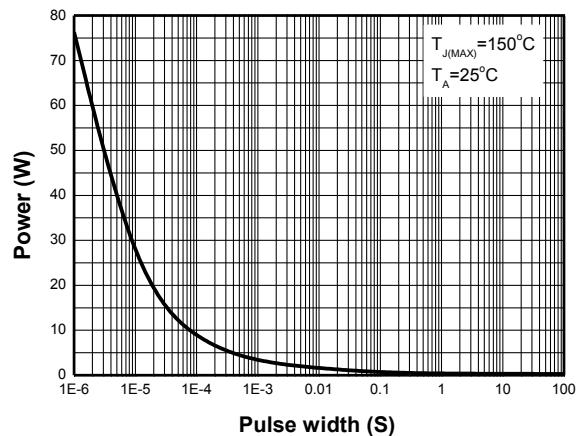
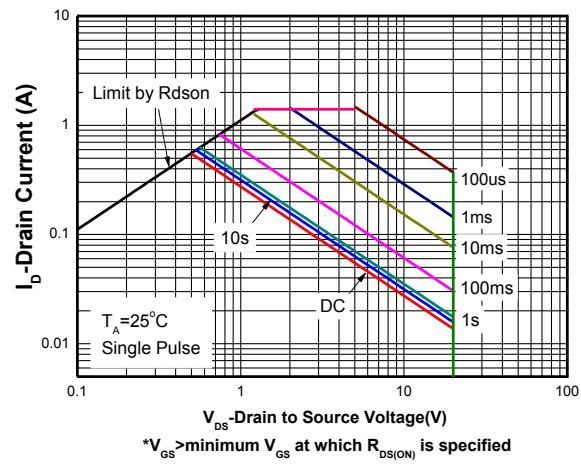
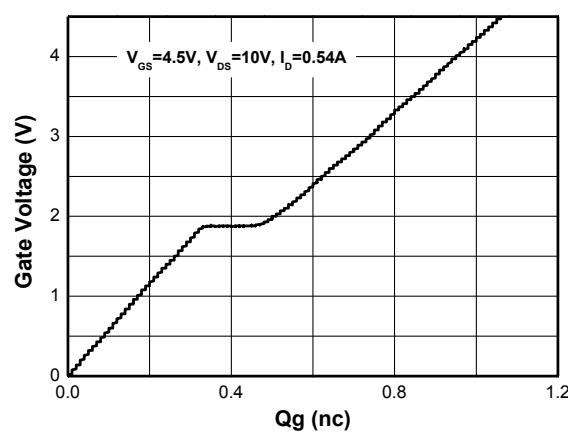
Parameter		Symbol	Typical	Maximum	Unit
Junction-to-Ambient Thermal Resistance ^a	t ≤ 10 s	R _{θJA}	350	390	°C/W
	Steady State		395	455	
Junction-to-Ambient Thermal Resistance ^b	t ≤ 10 s	R _{θJA}	397	435	°C/W
	Steady State		445	505	
Junction-to-Case Thermal Resistance	Steady State	R _{θJC}	240	280	

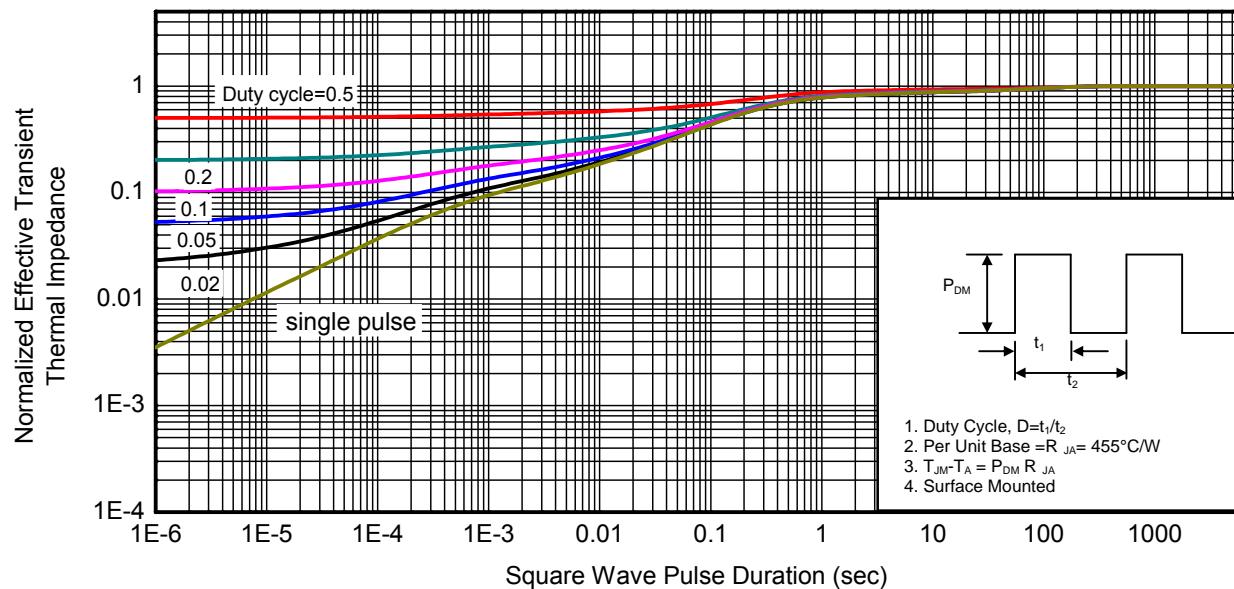
- a. Surface mounted on FR4 Board using 1 in sq pad size, 1oz Cu.
- b. Surface mounted on FR4 board using the minimum recommended pad size, 1oz Cu.
- c. Repetitive rating, pulse width limited by junction temperature, tp=10µs, Duty Cycle=1%.
- d. Repetitive rating, pulse width limited by junction temperature TJ(MAX)=150°C.

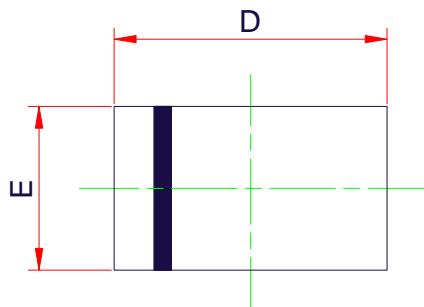
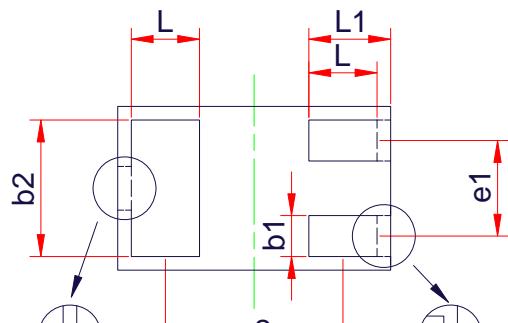
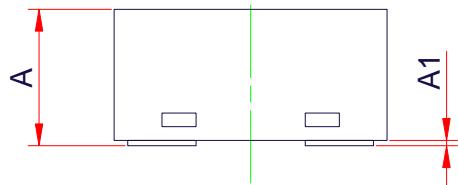
Electronics Characteristics (Ta=25°C, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0 V, I _D = 250uA	20			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 16V, V _{GS} = 0V			1	uA
Gate-to-source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±10V			±5	uA
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} = V _{DS} , I _D = 250uA	0.45	0.70	1.0	V
Drain-to-source On-resistance	R _{DS(on)}	V _{GS} = 4.5V, I _D = 0.35A		420	600	mΩ
		V _{GS} = 3.1V, I _D = 0.20A		500	700	
		V _{GS} = 2.5V, I _D = 0.20A		580	800	
		V _{GS} = 1.8V, I _D = 0.20A		840	1300	
		V _{GS} = 1.5V, I _D = 0.04A		1100	1600	
Forward Transconductance	g _{FS}	V _{DS} = 10 V, I _D = 0.35A		0.85		S
CHARGES, CAPACITANCES AND GATE RESISTANCE						
Input Capacitance	C _{iss}	V _{GS} = 0 V, f = 1.0MHz, V _{DS} = 10 V		30		pF
Output Capacitance	C _{oss}			7		
Reverse Transfer Capacitance	C _{RSS}			5		
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 4.5 V, V _{DS} = 10 V, I _D = 0.54 A		1.07		nC
Threshold Gate Charge	Q _{G(TH)}			0.12		
Gate-to-Source Charge	Q _{GS}			0.32		
Gate-to-Drain Charge	Q _{GD}			0.14		
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	td(ON)	V _{GS} = 4.5 V, V _{DS} = 10 V, I _D = 0.54A, R _G = 6Ω		7.2		ns
Rise Time	tr			9.5		
Turn-Off Delay Time	td(OFF)			19.6		
Fall Time	tf			4.6		
BODY DIODE CHARACTERISTICS						
Forward Voltage	V _{SD}	V _{GS} = 0 V, I _s = 0.3A		0.85	1.5	V

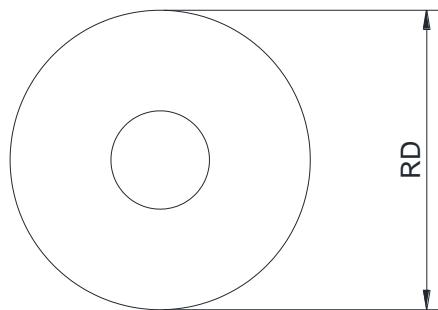
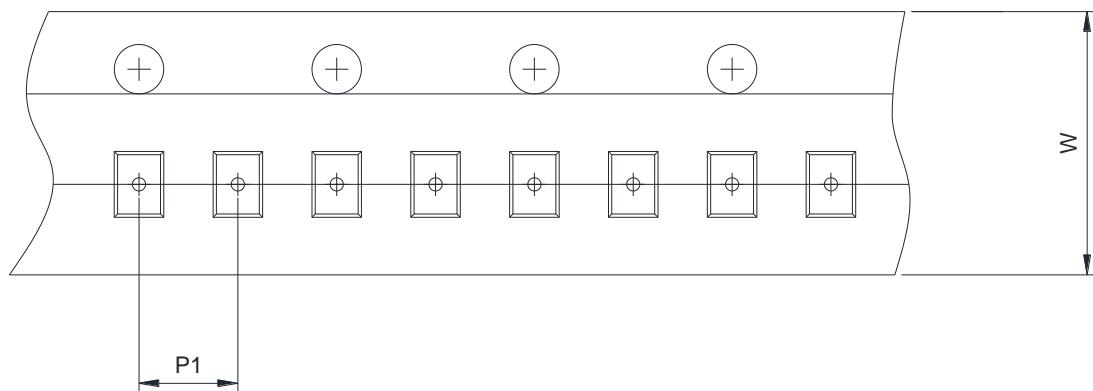
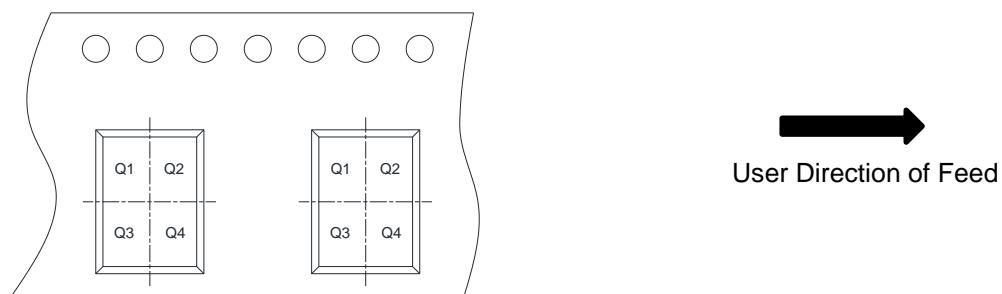
Typical Characteristics (Ta=25°C, unless otherwise noted)



Capacitance

Body diode forward voltage

Single pulse power

Safe operating power

Gate Charge Characteristics

Transient thermal response (Junction-to-Ambient)


Package outline dimensions
DFN1006-3L

TOP VIEW

BOTTOM VIEW

SIDE VIEW

Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	0.36	-	0.50
A1	0.00	-	0.05
D	0.95	1.00	1.05
E	0.55	0.60	0.65
b1	0.10	0.15	0.20
b2	0.40	0.50	0.60
L	0.20	0.25	0.30
L1	0.20	0.30	0.40
e1	0.35 BSC		
e2	0.65 BSC		

Package outline dimensions
Reel Dimensions

Tape Dimensions

Quadrant Assignments For PIN1 Orientation In Tape


RD	Reel Dimension	<input checked="" type="checkbox"/> 7inch <input type="checkbox"/> 13inch
W	Overall width of the carrier tape	<input checked="" type="checkbox"/> 8mm <input type="checkbox"/> 12mm <input type="checkbox"/> 16mm
P1	Pitch between successive cavity centers	<input checked="" type="checkbox"/> 2mm <input type="checkbox"/> 4mm <input type="checkbox"/> 8mm
Pin1	Pin1 Quadrant	<input type="checkbox"/> Q1 <input type="checkbox"/> Q2 <input checked="" type="checkbox"/> Q3 <input checked="" type="checkbox"/> Q4